

Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.9)
LeadCount	52
Option	Pb Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica Fused	72.61	2.72 E-01	526073
Epoxy, Cresol Novolac	19.36	7.24 E-02	140267
Phenol Resin	4.84	1.81 E-02	35066
Antimony Trioxide	1.45	5.42 E-03	10506
Brominated Epoxy Resin	1.45	5.42 E-03	10506
Carbon Black	0.29	1.09 E-03	2102

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	193867
Ni	3.00	6.80 E-04	1317
Si	0.65	3.14 E-03	6083
Mg	0.15	1.57 E-04	304

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100.0	1.04 E-03	2009

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	5.53 E-03	10704

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	1.45 E-03	2803

Chip			
	% of Chip	Weight (g)	PPM
Si	100.0	2.78 E-02	53861

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	72.5	1.70 E-03	3284
Epoxy Resin	7.5	1.75 E-04	339
Amine	5.0	1.17 E-04	227
Gamma Butyrolactone	5.0	1.17 E-04	227
Diglycidylether of bisphenol-f	5.0	1.17 E-04	227
Mixed aryl glycidyl compound	5.0	1.17 E-04	227

Molding Compound		
Item	PPM	Method
Pb	None Detected	US EPA 3052, ICP-OES
Cd	None Detected	US EPA 3052, ICP-OES
Hg	None Detected	US EPA 3052, ICP-OES
Cr+6	None Detected	US EPA 3060A & 7196A, UV-VIS
PBB	None Detected	Analysis was performed by GC/MS
PBDE	None Detected	Analysis was performed by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	3	US EPA 3052, ICP-OES
Cd	None Detected	US EPA 3052, ICP-OES
Hg	None Detected	US EPA 3052, ICP-OES
Cr+6	None Detected	US EPA 3060A & 7196A, UV-VIS
PBB	None Detected	Analysis was performed by GC/MS
PBDE	None Detected	Analysis was performed by GC/MS

Package Totals	
Weight (g)	PPM
5.16 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



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Si	0.65	3.14 E-03	6083
Mg	0.15	1.57 E-04	304

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100.0	1.04 E-03	2009

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	4.70 E-03	9098
Pb	15	8.29 E-04	1606

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	1.45 E-03	2803

Chip			
	% of Chip	Weight (g)	PPM
Si	100.0	2.78 E-02	53861

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